

**CLEANING SUBSTRATE FOR CLEANING  
AND REGENERATING A MOLD**

**ABSTRACT**

5 A cleaning substrate for cleaning and regenerating a mold is disclosed. The mold is contaminated after repeatedly packaging the semiconductor device by making use of thermosetting resin. At least a protrusion of the substrate can substantially match with and be contained within the edges of the mold cavity of the mold when the cleaning substrate is placed in the mold.

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